CENTERLINE TECHNOLOGIES

Die Level Lapping & Polishing

Centerline Technologies — relying on our extensive knowledge in lapping and polishing — is pleased to offer die level lapping and polishing. With precision machines and tooling, we are capable of lapping and polishing parts as small as 7mm square to 26mm square.

Materials Processed:

- Quartz
- Alumina
- Lithium Niobate
- Sapphire
- Composites
- AlN
- Hybrid Circuits

Typical thickness tolerances for die level application +/- 10 microns (tighter tolerances available upon request). Utilizing our proprietary processes and tooling, we are capable of angular lapping and polishing to tolerances of +/-0.05'.

Benefits to die level lapping and polishing are as follows:

- Better optical finishes
- Angular lapping and polishing
- Edge polish
- Less risk of yield loss from stress fractures

Centerline Technologies takes great pride in producing a superior product consistently and repeatedly. Please review our capabilities and polishing and lapping information. Talk to us. Ask questions. Find out why Centerline Technologies should be your preferred source for high quality polished and lapped substrate materials.